


Chokes for Power Lines

Material Data Sheet

Product Class:	Ring Core Triple Choke B82747S6313N061	
Date	28.02.2012	
IMDS ID if available		
Version:	01	

Product Part (IMDS: semi component)	Material Class (IMDS: Material)	Material (Classification) VDA 231	Substance	TMPS** [wt%]	CAS if applicable	typical mass of material [wt-%]	Traces see 1)
Active Part	Ceramic	4B	Manganese-Zinc ferrite	100	12645-49-7	62.6	
	Polymer	2C	Epoxy (EP)	100	25068-38-6	2.3	
	Metal	1C	Cu	100	7440-50-8	27.2	
	Polymer	2C	Polyester-imide (THEIC)	50	839-90-7	1.3	
			Polyamide-imide (PAI)	50	31957-38-7		
Encapsulation and Mounting	Polymer	2A	Polycarbonate (PC)	90	24936-68-3	2.7	
			Fiberglass	10	65997-17-3		
	Polymer	2A	Polyamide 66 (PA66)	75	32131-17-2	1.1	
			Fiberglass	25	65997-17-3		
	Polymer	2C	Polyurethane (PUR)	100	68400-67-9	1.6	
	Polymer	2A	Polyethylene terephthalate (PET)	100	25038-59-9	1.1	
Termination	Metal	1C	Sn	100	7440-31-5		x
Label	Polymer	2C	Polyethylenterephthalate (PET)	100	25038-59-9	0.1	
	Polymer	2C	Acrylic resin	100	37325-11-4		X
Sum in total:						100.0	

Size W x L x H [max. in mm]	Weight [approx. in g]	Part Numbers
Ø 64x39	186	B82747S6313N061

Not part of a Product Class		
Contact	Dr. Johann Reindl, MAG EPQM	Important remarks: 1) The declaration limit is 0.1% as defined by IEC 62474 (IEC PAS 61906) Traces are product parts, substances etc. that are below a percentage of 0.1 % by weight, if not otherwise regulated. 2) This Material Data Sheet contains typical values of the respective products set forth herein. We expressly point out that all values and statements contained herein are based on our best present knowledge and cannot be regarded as binding statements or binding product specifications, unless otherwise explicitly agreed in writing. TDK ELECTRONICS AG AND ITS AFFILIATES HEREBY EXPRESSLY DISCLAIM ANY REPRESENTATION OR WARRANTY, WHETHER EXPRESS, IMPLIED OR STATUTORY, WITH REGARD TO THE STATEMENTS AND VALUES CONTAINED HEREIN, INCLUDING BUT NOT LIMITED TO ANY REPRESENTATION OR WARRANTY OF MERCHANTABILITY OR SUITABILITY FOR ANY PURPOSE.
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*) others: (not declarable or prohibited substances acc. GADSL)		
**) typical mass percentage of substance		

The products set forth herein are "RoHS-compatible". RoHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

RoHS - Exemptions for the Product Class / Product according to Annex III: (<input checked="" type="checkbox"/> valid <input type="checkbox"/> not valid) <input checked="" type="checkbox"/> no exemptions; <input type="checkbox"/> Exemption 6 (a): Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0,35 % lead by weight; <input type="checkbox"/> Exemption 6 (b): Lead as an alloying element in aluminium containing up to 0,4 % lead by weight; <input type="checkbox"/> Exemption 6 (c): Copper alloy containing up to 4 % lead by weight; <input type="checkbox"/> Exemption 7 (a): Lead in high melting temperature type solder (i.e. lead-based alloys containing 85 % by weight or more lead); <input type="checkbox"/> Exemption 7 (c)-I: Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound; <input type="checkbox"/> Exemption 7 (c)-II: Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher; <input type="checkbox"/> Exemption 7 (c)-III: Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC; <input type="checkbox"/> Exemption 15: Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages; <input type="checkbox"/> Other Exemption than above
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